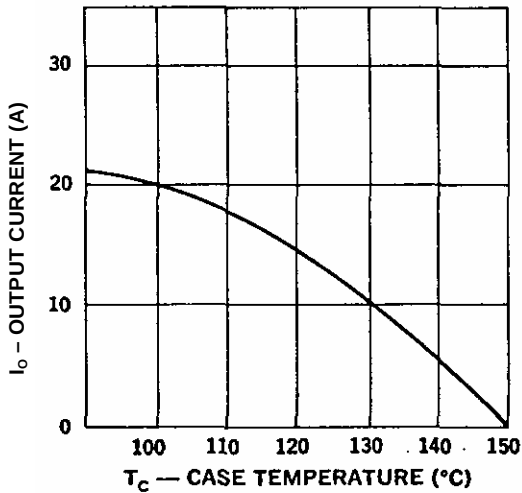
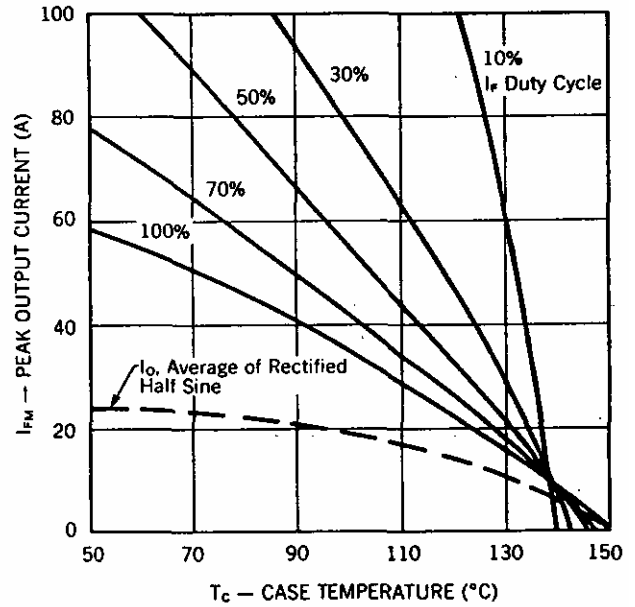


OUTLINE AND CIRCUIT

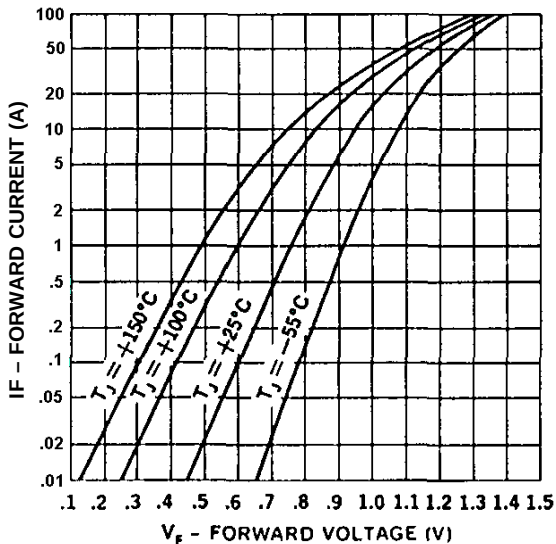
Output Current vs.
Case Temperature



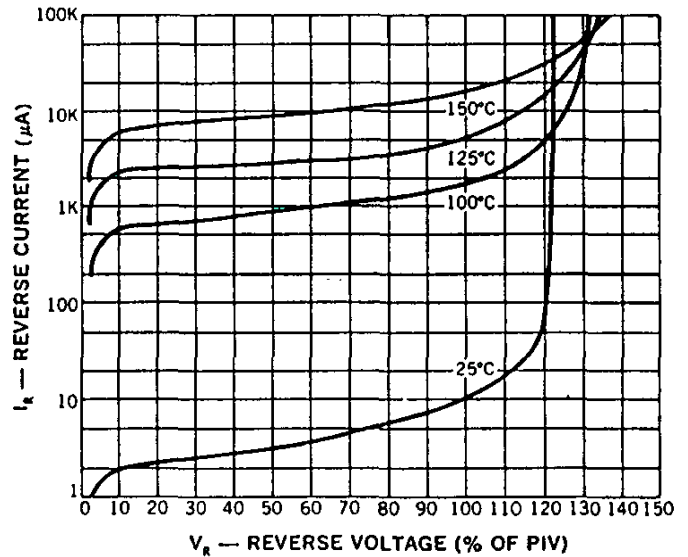
Peak Output Current vs.
Case Temperature



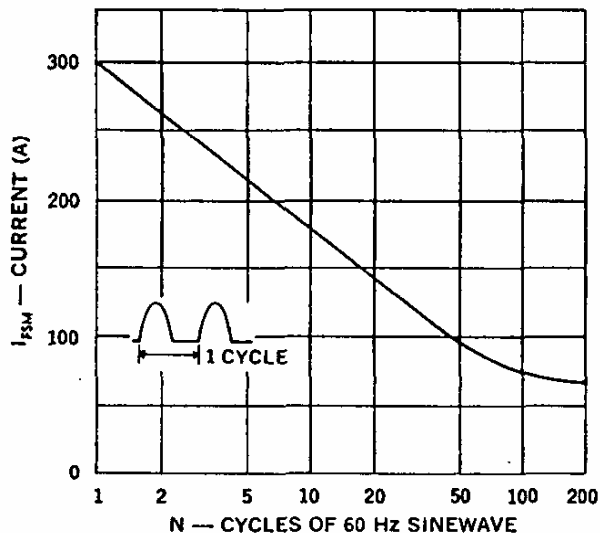
Typical Forward Current
vs. Forward Voltage



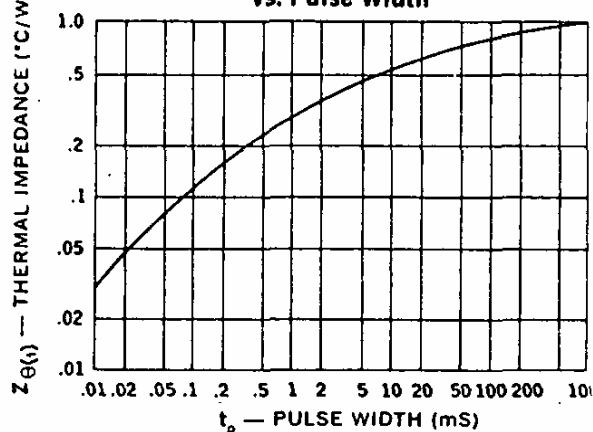
Typical Reverse Current
vs. Reverse Voltage



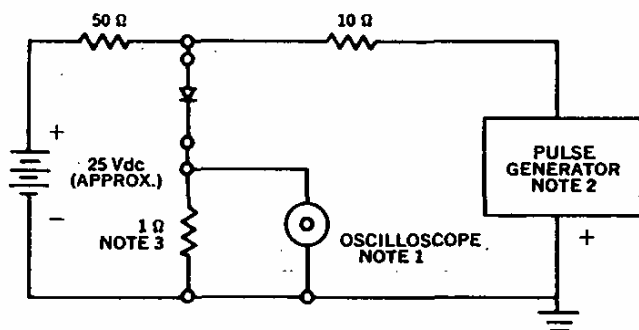
**Maximum Forward Surge
vs. Number of Cycles**



**Thermal Impedance
vs. Pulse Width**



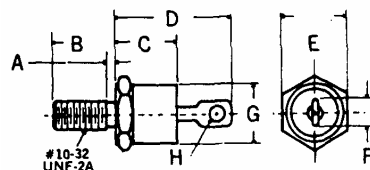
Reverse-Recovery Circuit



NOTES:

1. Oscilloscope: Rise time ≤ 3 ns; input impedance = 50 Ω .
2. Pulse Generator: Rise time ≤ 8 ns; source impedance 10 Ω .
3. Current viewing resistor, non-inductive, coaxial recommended.

**MECHANICAL
SPECIFICATIONS**



	INCHES	MM
A	.078 MAX	1.98 MAX.
B	.437 +/- .015	11.10 +/- 0.38
C	.405 MAX	10.29 MAX.
D	.800 MAX	20.32 MAX.
E	.430 +/- .010	10.92 +/- 0.25
F	.250 MAX	6.35 MAX.
G	.424 MAX	10.77 MAX.
H	.066 MIN. DIA	1.68 MIN. DIA

Notes:

1. Cathode is stud.
2. All metal surfaces tin plated.
3. Maximum unlubricated stud torque: 10 inch pounds.
4. Angular Orientation of terminal is undefined.

OPTIONAL HIGH RELIABILITY (HR2) SCREENING

The following tests are performed on 100% of the devices.

SCREEN	MIL-STD-750 METHOD	CONDITIONS
1. High Temperature	1032	24 Hours @ TA = 150°C
2. Temperature Cycle	1051	F, 20 Cycles, -55 to +150°C. No dwell required @ 25°C, T ₁ ≥ 10 min. @ extremes
3. Hermetic Seal a. Fine Leak b. Gross Leak	1071	H, Helium C, Liquid
4. Thermal Impedance	3101	
5. Interim Electrical Parameters	GO/NO GO	As applicable
6. High Temperature Reverse Blocking	As Applicable	t = 48 hours, T _c = 125°C with applicable bias conditions
7. Final Electrical Parameters	GO/NO GO	As applicable